

# HSM124S

Silicon Epitaxial Planar Diode for Switching

# HITACHI

ADE-208-041D (Z)

Rev. 4

Aug. 1995

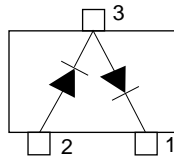
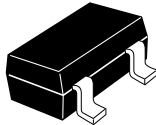
## Features

- Low reverse current.
- MPAK package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HSM124S	A1	MPAK

## Pin Arrangement



(Top View)

- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1  
Anode 2

**Absolute Maximum Ratings**\*<sup>2</sup> (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	80	V
Reverse voltage	$V_R$	85	V
Peak forward current	$I_{FM}$	300	mA
Non-Repetitive peak forward surge current	$I_{FSM}^{*1}$	4	A
Average forward current	$I_O$	100	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Within 1μs forward surge current.

2. Per one device

**Electrical Characteristics**\* (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	—	—	1.0	V	$I_F = 10\text{mA}$
	$V_{F2}$	—	—	1.0		$I_F = 50\text{mA}$
	$V_{F3}$	—	—	1.2		$I_F = 100\text{mA}$
Reverse current	$I_R$	—	—	0.01	μA	$V_R = 80\text{V}$
Capacitance	C	—	—	4.0	pF	$V_R = 0\text{V}, f = 1\text{MHz}$
Reverse recovery time	$t_{rr}$	—	—	100	ns	$I_F = 10\text{mA}, V_R = 6\text{V}, R_L = 50\Omega$

Note: Per one device

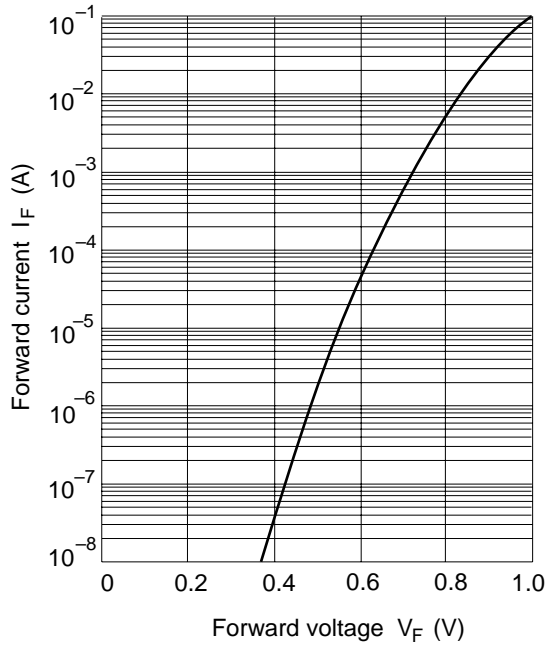


Fig.1 Forward current Vs. Forward voltage

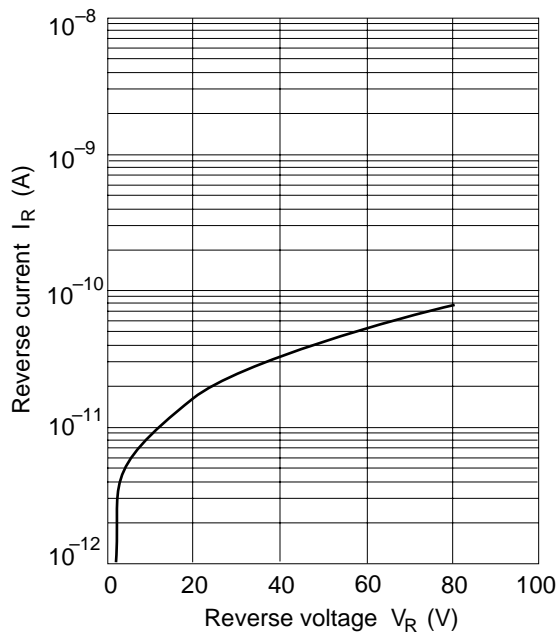


Fig.2 Reverse current Vs. Reverse voltage

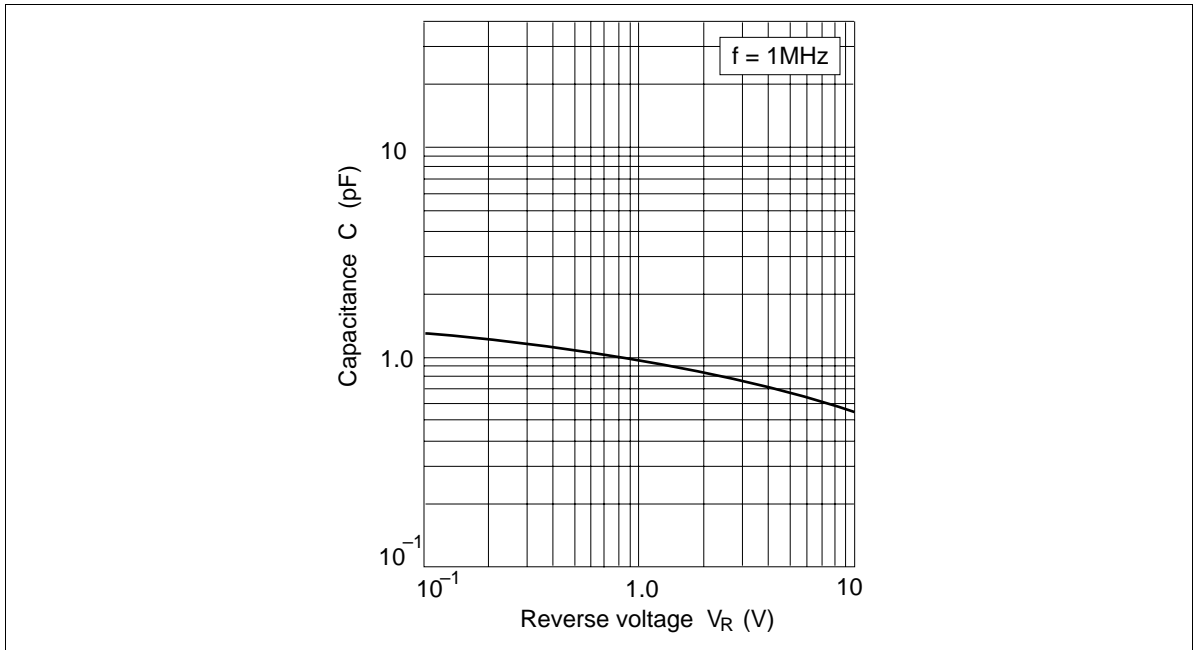
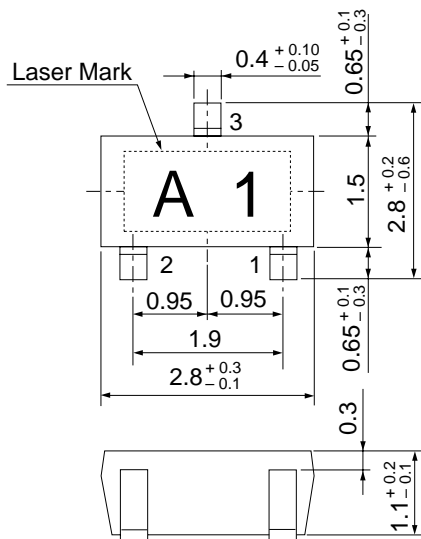


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1
- Anode 2

HITACHI Code	MPAK(1)
JEDEC Code	—
EIAJ Code	SC-59A
Weight (g)	0.011

## Cautions

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